

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID	Unique ID Authority	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 09, 2014 04:04 AM
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Ite	m Number	Mfr Item Name	Effective Date	Version	N	Manufacturing Site	Weight*	UOM	Unit Type	
QSD2030F	QSI	02030F	T1 3/4 5mm			SUB	CONTRACTOR	0.301625	g	Each	
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-0	20 MSL Rating	Peak Process Bo	dy Tempera	ture	Max Time at Peak Temperature		No Ret	No Reflow cycles	
Matte Tin (Sn)	Other	Not A	Applicable	C			seconds		Not A	Not Applicable	

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name T1 3/4 5mm

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.000	Supplier		Gallium Arsenide	0.000	1303-00-0	0
			Supplier		Silicon	0.000	7440-21-3	0
Die Attach	Other Organic Materials	0.000	Supplier		Phenolic resin	0.000	54208-63-8	0
			Supplier		Silver	0.000	7440-22-4	0
Encapsulation	Thermoplastics	202.000	Supplier		Epoxy Resin	101.000	29690-82-2	334853
			Supplier		Ethylene Glycol	4.040	107-21-1	13394
			Supplier		Methylhexahydrophthalic anhydride	92.920	25550-51-0	308065
			Supplier		Tetraethyl Ammonia Bromide	4.040	71-91-0	13394
Lead Frame	Other Ferrous alloys, non-stainless steels	82.900	Supplier		Carbon	0.415	7440-44-0	1374
			Supplier		Iron	82.304	7439-89-6	272869
			Supplier		Manganese	0.083	7439-96-5	275
			Supplier		Phosphorus	0.041	7723-14-0	137
			Supplier		Silver	0.016	7440-22-4	52
			Supplier		Sulfur	0.041	7704-34-9	137
Plating	Other Nonferrous metals & alloys	16.700	Supplier		Tin	16.700	7440-31-5	55367
Wire Bond	Precious metals	0.025	Supplier		Gold	0.025	7440-57-5	82